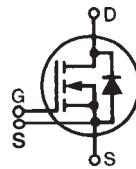


LinearL2™
Power MOSFET w/
Extended FBSOA

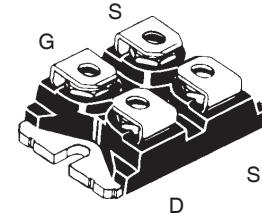
IXTN240N075L2

N-Channel Enhancement Mode
Avalanche Rated



V_{DSS} = 75V
I_{D25} = 225A
R_{DS(on)} ≤ 7mΩ

miniBLOC, SOT-227
 E153432



G = Gate D = Drain
S = Source

Either Source Terminal S can be used as the Source Terminal or the Kelvin Source (Gate Return) Terminal.

Symbol	Test Conditions		Maximum Ratings	
V _{DSS}	T _J = 25°C to 150°C		75	V
V _{DGR}	T _J = 25°C to 150°C, R _{GS} = 1MΩ		75	V
V _{GSS}	Continuous		±20	V
V _{GSM}	Transient		±30	V
I _{D25}	T _C = 25°C (Chip Capability)		225	A
I _{L(RMS)}	External Lead Current Limit		200	A
I _{DM}	T _C = 25°C, pulse width limited by T _{JM}		720	A
I _A	T _C = 25°C		240	A
E _{AS}	T _C = 25°C		3	J
P _D	T _C = 25°C		735	W
T _J			-55...+150	°C
T _{JM}			150	°C
T _{stg}			-55...+150	°C
V _{ISOL}	50/60 Hz, RMS I _{ISOL} ≤ 1mA	t = 1 minute t = 1 second	2500 3000	V~ V~
M _d	Mounting Torque Terminal Connection Torque		1.5/13 1.3/11.5	Nm/lb.in Nm/lb.in
Weight			30	g

Symbol	Test Conditions (T _J = 25°C, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0V, I _D = 1mA	75		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 3mA	2.0		4.5 V
I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±200 nA
I _{DSS}	V _{DS} = V _{DSS} , V _{GS} = 0V T _J = 125°C			10 μA 50 μA
R _{DS(on)}	V _{GS} = 10V, I _D = 120A, Note 1			7 mΩ

Features

- Designed for Linear Operation
- International Standard Package
- Guaranteed FBSOA at 75°C
- Avalanche Rated
- Molding Epoxy Meets UL94 V-0 Flammability Classification
- MiniBLOC with Aluminium Nitride Isolation

Advantages

- Easy to mount
- Space savings
- High power density

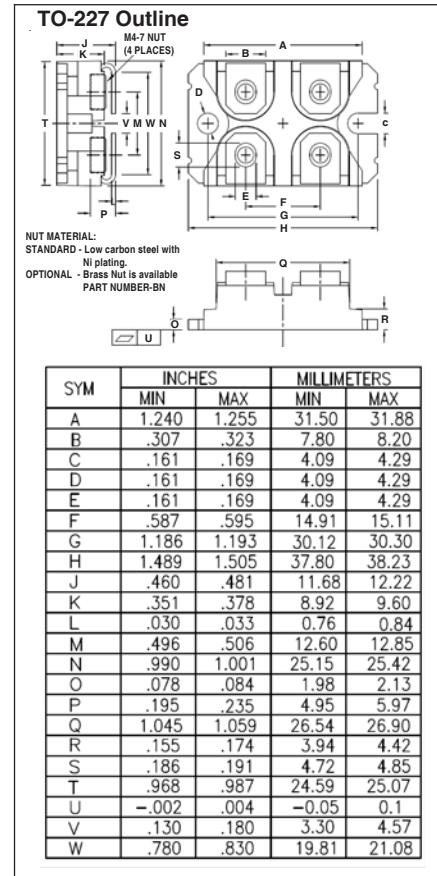
Applications

- Solid state circuit breakers
- Soft start controls
- Linear amplifiers
- Programmable loads
- Current regulators

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 60\text{A}$, Note 1	60	86	110 S
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	19		nF
		4420		pF
		1470		pF
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 120\text{A}$ $R_G = 1\Omega$ (External)	34		ns
		200		ns
		136		ns
		47		ns
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 120\text{A}$	546		nc
		86		nc
		225		nc
R_{thJC}			0.17	$^\circ\text{C}/\text{W}$
R_{thCS}		0.05		$^\circ\text{C}/\text{W}$

Safe Operating Area Specification

Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
SOA	$V_{DS} = 75\text{V}$, $I_D = 5.9\text{A}$, $T_C = 75^\circ\text{C}$, $T_p = 5\text{s}$	440		W



Source-Drain Diode

Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
($T_J = 25^\circ\text{C}$, unless otherwise specified)				
I_s	$V_{GS} = 0\text{V}$		240	A
I_{SM}	Repetitive, pulse width limited by T_{JM}		960	A
V_{SD}	$I_F = 100\text{A}$, $V_{GS} = 0\text{V}$, Note 1		1.5	V
t_{rr} I_{RM} Q_{RM}	$I_F = 120\text{A}$, $-\text{di/dt} = 100\text{A}/\mu\text{s}$, $V_R = 37.5\text{V}$, $V_{GS} = 0\text{V}$	206		ns
		18.8		A
		1.9		μC

Note: 1. Pulse test, $t \leq 300\mu\text{s}$; duty cycle, $d \leq 2\%$.

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

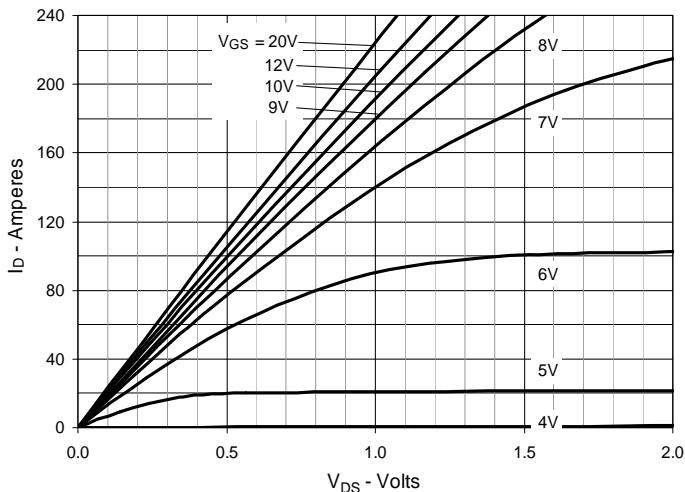
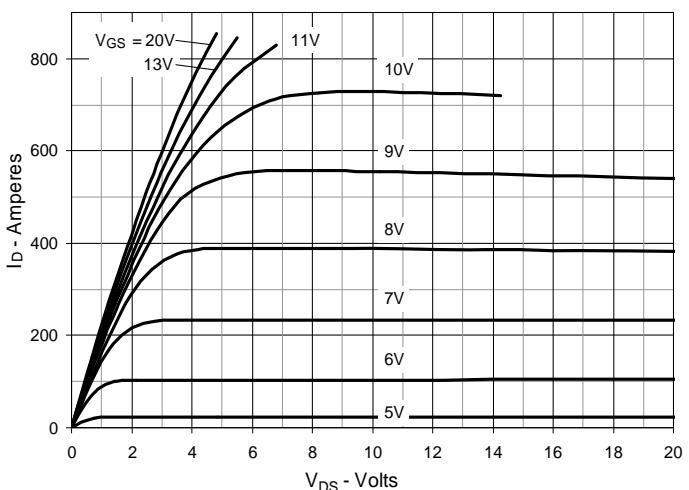
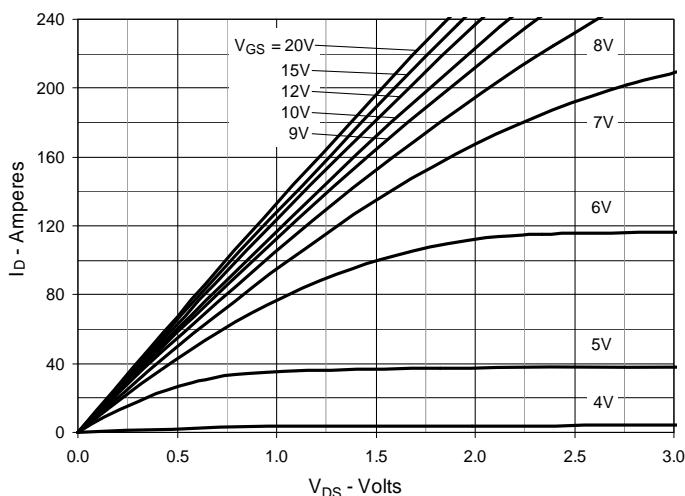
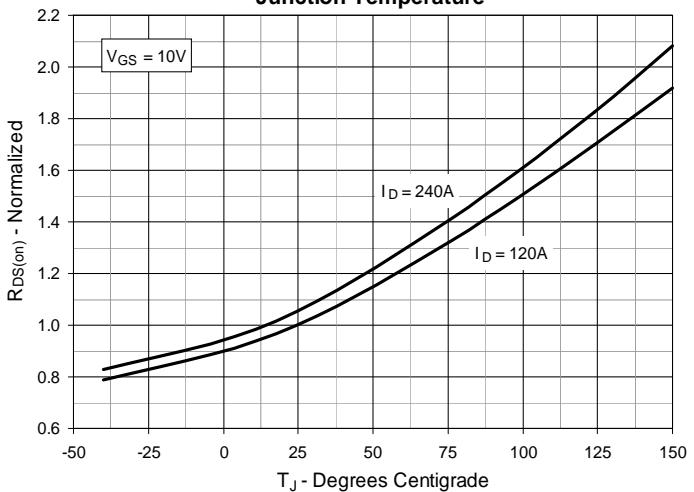
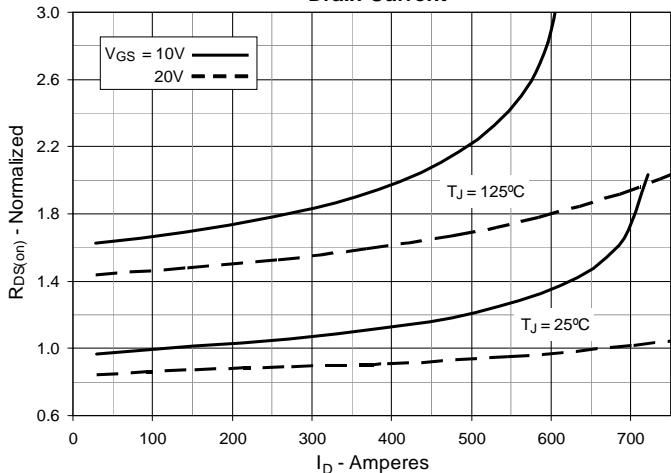
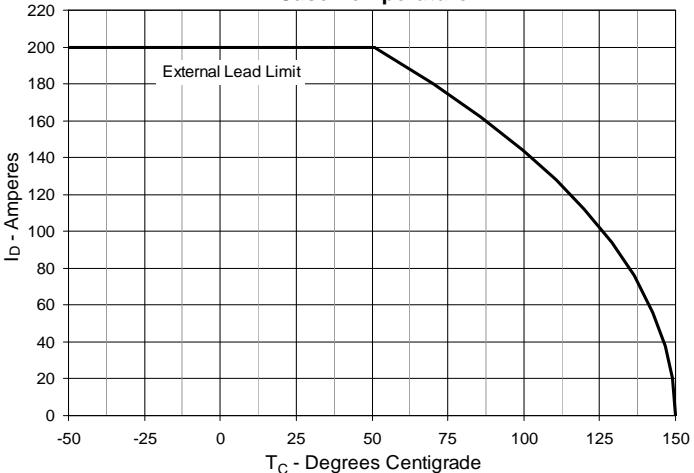
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ **Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$** **Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$** **Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 120\text{A}$ Value vs. Junction Temperature****Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 120\text{A}$ Value vs. Drain Current****Fig. 6. Maximum Drain Current vs. Case Temperature**

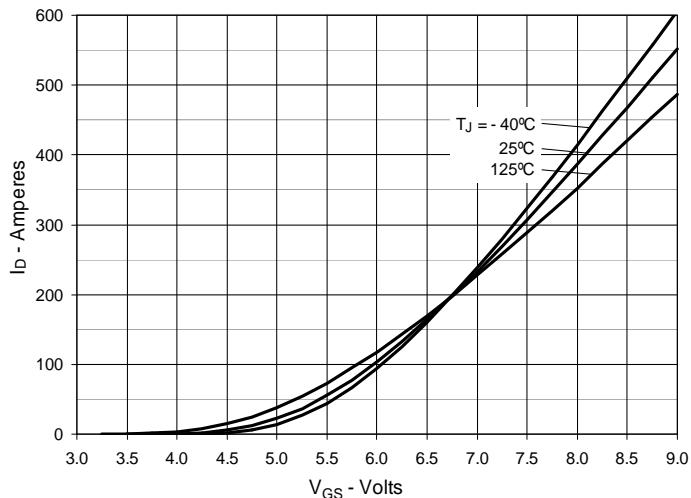
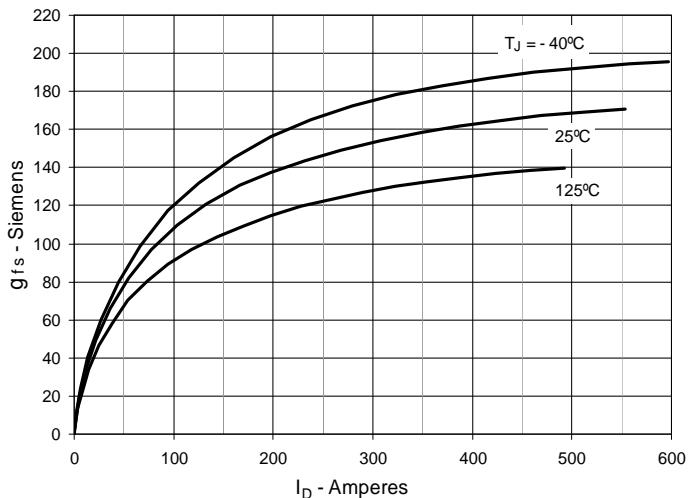
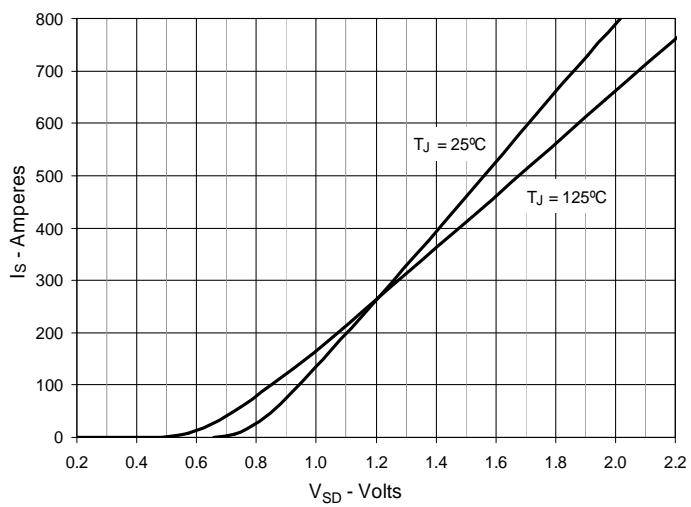
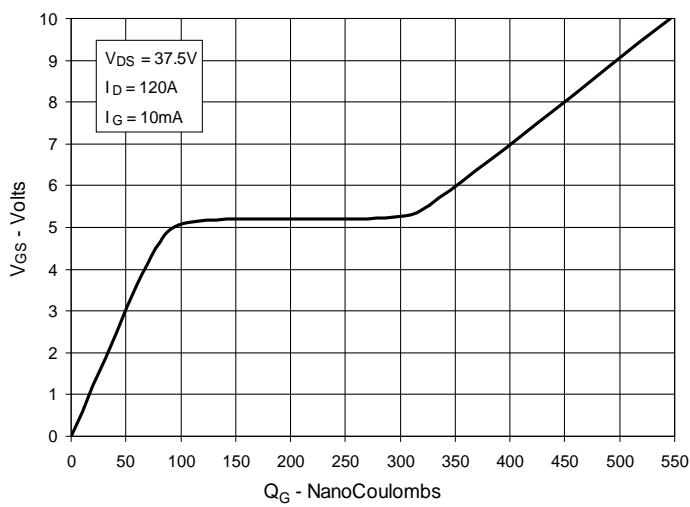
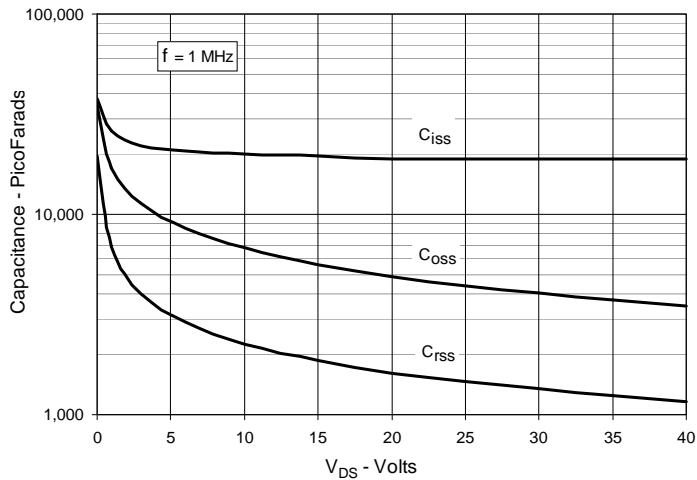
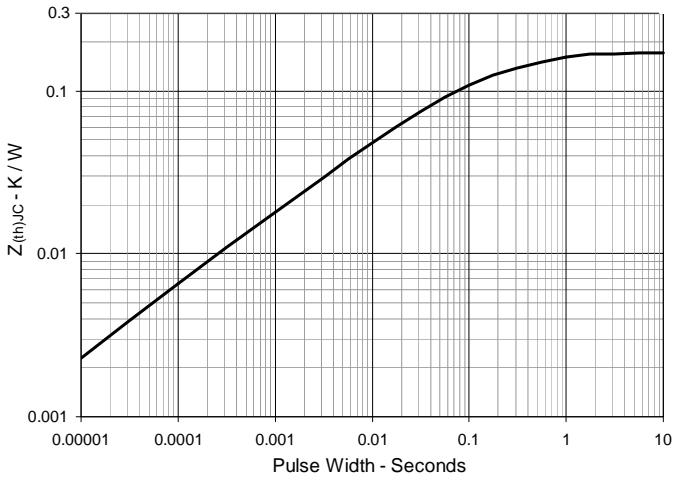
Fig. 7. Input Admittance**Fig. 8. Transconductance****Fig. 9. Forward Voltage Drop of Intrinsic Diode****Fig. 10. Gate Charge****Fig. 11. Capacitance****Fig. 12. Maximum Transient Thermal Impedance**

Fig. 13. Forward-Bias Safe Operating Area
@ $T_C = 25^\circ\text{C}$

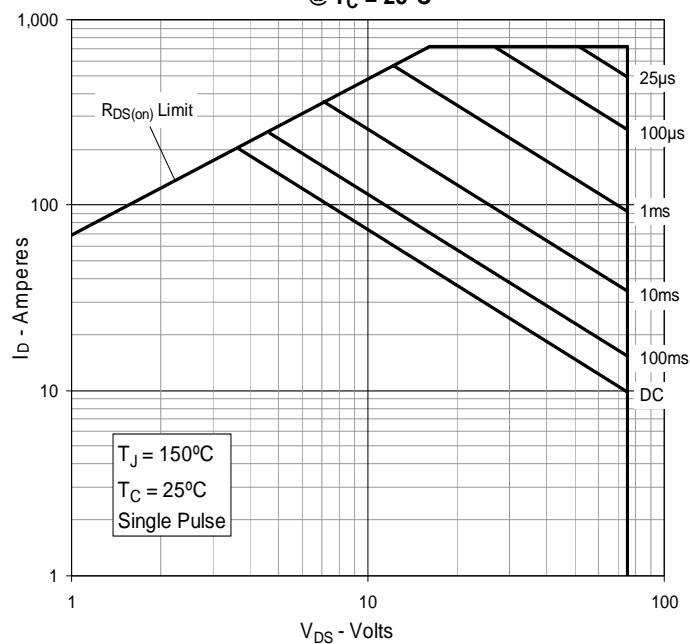


Fig. 14. Forward-Bias Safe Operating Area
@ $T_C = 75^\circ\text{C}$

